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(21) International Application Number: PCT/US96/12759 (22) International Filing Date: 9 August 1996 (09.08.96) (30) Priority Data: 08/514,049 11 August 1995 (11.08.95) US 08/644,912 28 May 1996 (28.05.96) US (71)(72) Applicant and Inventor: KIRSTEN, Kenneth, J. [US/US]; 675 B Streamwood Boulevard, Streamwood, IL 60107 (US). (74) Agent: GEORGES, Peter, J.; Breneman & Georges, 3150 Commonwealth Avenue, Alexandria, VA 22305 (US).		(81) Designated States: JP, KR, SG, European patent (AT, BE, CH, DE, DK, ES, FI, FR, GB, GR, IE, IT, LU, MC, NL, PT, SE). Published <i>With international search report.</i> <i>Before the expiration of the time limit for amending the claims and to be republished in the event of the receipt of amendments.</i>
(54) Title: ENCAPSULANT WITH FLUXING PROPERTIES AND METHOD OF USE (57) Abstract Encapsulated electrical component assemblies and methods of electrically connecting an electrical component having a plurality of component electrical terminations to a component carrying substrate having a plurality of substrate electrical terminations at surface mount reflow soldering conditions is described. The electrical and substrate components have an encapsulant-forming composition sandwiched therebetween and encasing said pluralities of component and substrate electrical connections. The described invention relates to using an encapsulant-forming composition comprising a thermosetting resin (preferably an epoxy resin) and a cross-linking agent (preferably an anhydride) for said resin that cross-links said resin and that also acts as a fluxing agent and optionally includes a catalyst for initiating cross-linking at required conditions. The gel point of the encapsulant-forming composition is reached after solder melt.		